# Modeling a Circular Membrane Under Pressure

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## **Application: MEMS Pressure Sensor**

- Pressure increases membrane resonant freq.
- Size membranes under pressure to have same frequency range as other sensors
- Goal: do this analytically





## **Project Approach**

- Find resonant frequency of a membrane as a function of applied pressure
- Compare three methods:
  - Analytical (Hankel Transformation and SOV)
  - Numerical (Finite Element Analysis FEA)
  - Experimental (using MEMS pressure sensor)





## Analytical: Using Hankel Transforms



**Analytical - Using SOV:**  $\nabla^2 u(r,t) = \frac{1}{cm^2} u_{tt}(r,t) - \frac{P(r)}{T_m}$ Assume:  $u(r,t) = \psi(r) + \phi(r,t)$ Particular Homogeneous  $\frac{1}{r}\psi_r + \psi_{rr} = \frac{P_o}{T_m}$  $\frac{1}{r}\phi_r + \phi_{rr} = \frac{1}{cm^2}\phi_{tt}$ Solve with SOV ODE - Solve! - $\phi(r,t) = AJ_o\left(\frac{\lambda_i}{a}\right)\cos\left(\frac{cm\lambda_i}{a}t\right)$  $\psi(r) = -\frac{P_o}{4T_m}(a^2 - r^2)$  $u(r,t) = \frac{P_o}{T_m} \left| \frac{(a^2 - r^2)}{4} - 2a^2 \sum_{i=1,2}^{\infty} \frac{J_o(\frac{\lambda_i}{a}r)}{\lambda_i^3 J_1(\lambda_i)} \cos\left(\frac{\lambda_i cmt}{a}\right) \right|$ 

### **Analytic Conclusions**

Hankel and SOV produce the same expression



### **Finite Element Analysis - Approach**

COMSOL Multiphysics was used to implement numerical solution

- Model
  - Axisymmetric 2D model
  - Nonlinear, Large deformations
- Boundary Conditions
  - Clamped edge
  - Symmetry
- Load
  - Pressure
- Analysis
  - Static
  - Prestressed Eigenfrequency



Axial Symmetry (membrane CENTER)

Material Property	Aluminum Nitride
Density (kg/m³)	3260
Young's Modulus (Pa)	340 × 10 <sup>9</sup>
Poisson's Ratio	0.3

### **Results: Mode Shape**



Analytical Result

**FEA Result** 

## **Results: Video**



Analytical Result

#### Experimental Setup & MEMs Chip



Actual MEMs Pressure Sensor on a chip







#### **Results: Frequency vs. Pressure**



### Sources of error $\rightarrow$ Future Work

- Damping effects squeeze film damping
- Substrate interaction
- Initial stress estimation of released film





Spring-Damper model for Squeeze film damping

### **Acknowledgements**

#### Fabian Goericke, GSR who helped take experimental measurements

### **Key References**

- Selvadurai A., "Partial Differential Equations in Mechanics"
- Reynolds, "Introduction to PDEs Class Notes"

Thank You. Any Questions?